



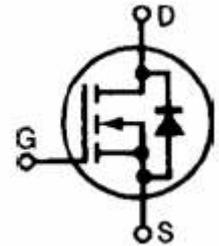
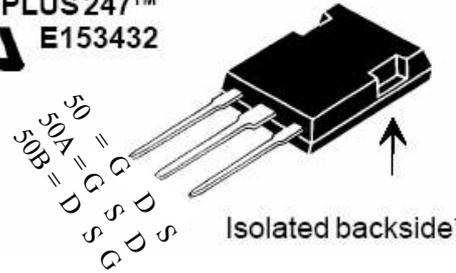
IXZR18N50 & IXZR18N50A/B
Z-MOS RF Power MOSFET

N-Channel Enhancement Mode Switch Mode RF MOSFET
Low Capacitance Z-MOS™ MOSFET Process
Optimized for RF Operation
Ideal for Class C, D, & E Applications

V_{DSS} = 500 V
I_{D25} = 19 A
R_{DS(on)} ≤ 0.37 Ω
P_{DC} = 350 W

Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 150°C	500	V
V _{DGR}	T _J = 25°C to 150°C; R _{GS} = 1 MΩ	500	V
V _{GS}	Continuous	±20	V
V _{GSM}	Transient	±30	V
I _{D25}	T _c = 25°C	19	A
I _{DM}	T _c = 25°C, pulse width limited by T _{JM}	95	A
I _{AR}	T _c = 25°C	19	A
E _{AR}	T _c = 25°C	TBD	mJ
dv/dt	I _S ≤ I _{DM} , di/dt ≤ 100A/μs, V _{DD} ≤ V _{DSS} , T _J ≤ 150°C, R _G = 0.2Ω	5	V/ns
	I _S = 0	>200	V/ns
P _{DC}		350	W
P _{DHS}	T _c = 25°C, Derate 4.4W/°C above 25°C	TBD	W
P _{DAMB}	T _c = 25°C	3.0	W
R _{thJC}		TBD	C/W
R _{thJHS}		TBD	C/W

ISOPLUS247™
E153432



Symbol	Test Conditions	Characteristic Values		
		min.	typ.	max.
(T _J = 25°C unless otherwise specified)				
V _{DSS}	V _{GS} = 0 V, I _D = 4 ma	500		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA		4.6	V
I _{GSS}	V _{GS} = ±20 V _{DC} , V _{DS} = 0			±100 nA
I _{DSS}	V _{DS} = 0.8V _{DSS} V _{GS} =0 =125C	T _J = 25C T _J		50 μA
				1 mA
R _{DS(on)}	V _{GS} = 20 V, I _D = 0.5I _{D25} Pulse test, t ≤ 300μs, duty cycle d ≤ 2%		0.37	Ω
g _{fs}	V _{DS} = 50 V, I _D = 0.5I _{D25} , pulse test		6.7	S
T _J		-55		+175 °C
T _{JM}			175	°C
T _{stg}		-55		+ 175 °C
T _L	1.6mm(0.063 in) from case for 10 s		300	°C
Weight			3.5	g

Features

- Isolated Substrate
 - high isolation voltage (>2500V)
 - excellent thermal transfer
 - Increased temperature and power cycling capability
- IXYS advanced Z-MOS process
- Low gate charge and capacitances
 - easier to drive
 - faster switching
- Low R_{DS(on)}
- Very low insertion inductance (<2nH)
- No beryllium oxide (BeO) or other hazardous materials

Advantages

- Optimized for RF and high speed
- Easy to mount—no insulators needed
- High power density



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Symbol	Test Conditions	Characteristic Values (T _J = 25°C unless otherwise specified)		
		min.	typ.	max.
R _G				1 Ω
C _{iss}			2020	pF
C _{oss}	V _{GS} = 0 V, V _{DS} = 0.8 V _{DSS(max)} , f = 1 MHz		172	pF
C _{rss}			21	pF
C _{stray}	Back Metal to any Pin		33	pF
T _{d(on)}			4	ns
T _{on}	V _{GS} = 15 V, V _{DS} = 0.8 V _{DSS} I _D = 0.5 I _{DM}		4	ns
T _{d(off)}	R _G = 1 Ω (External)		4	ns
T _{off}			5	ns
Q _{g(on)}			42	nC
Q _{gs}	V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} I _D = 0.5 I _{D25} I _G = 3mA		14	nC
Q _{gd}			21	nC

Source-Drain Diode		Characteristic Values (T _J = 25°C unless otherwise specified)		
Symbol	Test Conditions	min.	typ.	max.
I _S	V _{GS} = 0 V			19 A
I _{SM}	Repetitive; pulse width limited by T _{JM}			114 A
V _{SD}	I _F = I _S , V _{GS} = 0 V, Pulse test, t ≤ 300μs, duty cycle ≤ 2%			1.5 V
T _{rr}			200	ns

CAUTION: Operation at or above the Maximum Ratings values may impact device reliability or cause permanent damage to the device.

Information in this document is believed to be accurate and reliable. IXYS RF reserves the right to make changes to information published in this document at any time and without notice.

IXYS RF reserves the right to change limits, test conditions and dimensions.

IXYS RF MOSFETS are covered by one or more of the following U.S. patents:

4,835,592	4,860,072	4,881,106	4,891,686	4,931,844	5,017,508
5,034,796	5,049,961	5,063,307	5,187,117	5,237,481	5,486,715
5,381,025	5,640,045	6,404,065	6,583,505	6,710,463	6,727,585
6,731,002					



**IXZR18N50 & IXZR18N50A/B
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Fig. 1 **Gate Charge vs. Gate-to-Source Voltage**
 $V_{DS} = 250V, I_D = 9.5A, I_G = 3mA$

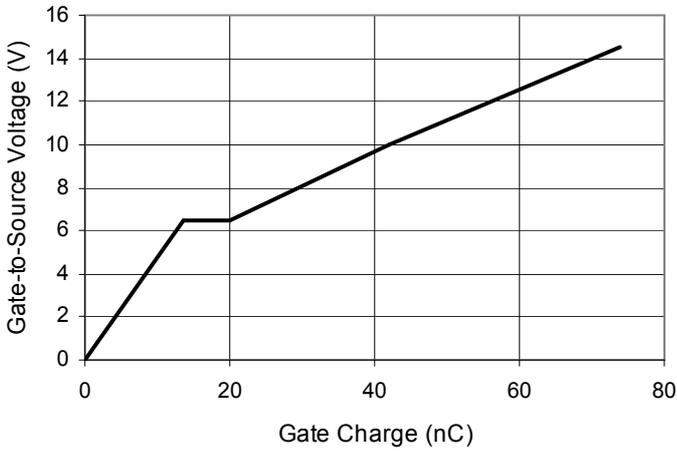


Fig. 2 **Typical Output Characteristics**

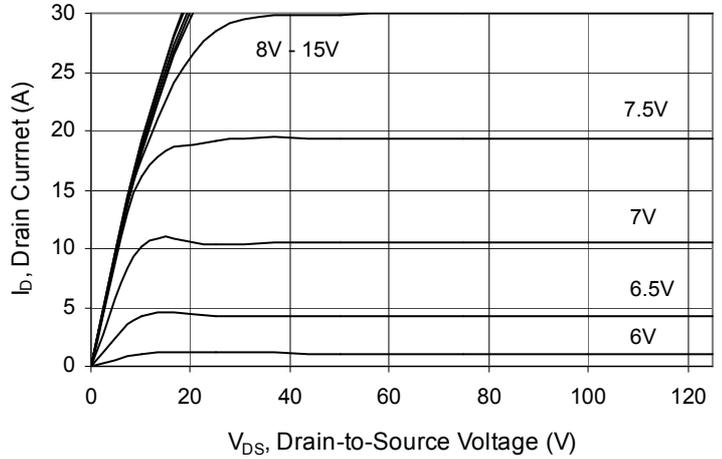


Fig. 3 **Typical Transfer Characteristics**
 $V_{DS} = 50V$

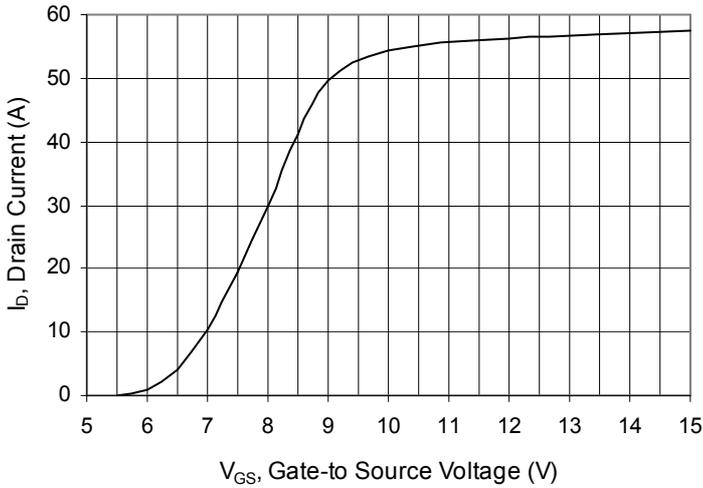


Fig. 4 **Extended Typical Output Characteristics**

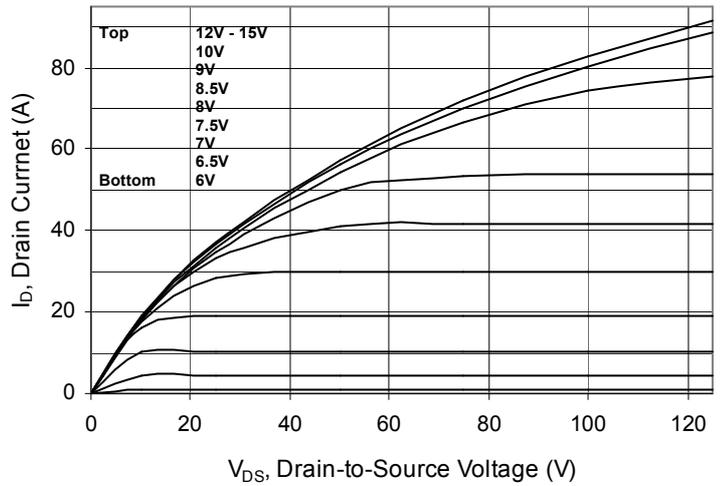
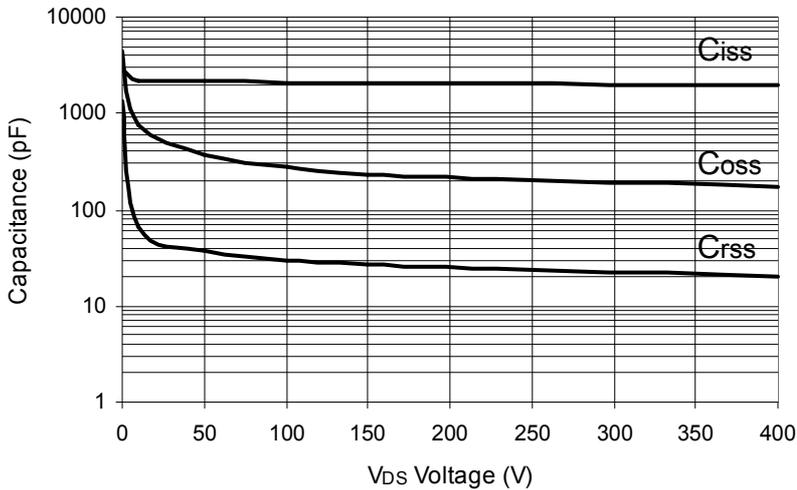


Fig. 5 **V_{DS} vs. Capacitance**

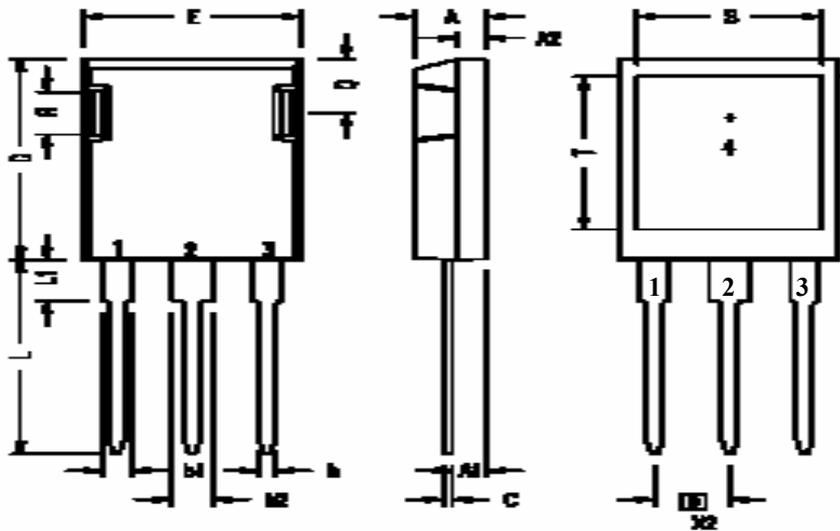




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Fig. 6 Package Drawing

ISOPLUS 247 OUTLINE



50: 1=G, 2=D, 3=S
50A: 1=G, 2=S, 3= D
50B: 1=D, 2=S, 3=G



1 Gate, 2 Drain (Collector)
3 Source (Emitter)
4 no connection

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.83	5.21	.190	.205
A ₁	2.29	2.54	.090	.100
A ₂	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b ₁	1.91	2.13	.075	.084
b ₂	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	.244
R	4.32	4.83	.170	.190

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An IXYS Company
2401 Research Blvd., Suite 108
Fort Collins, CO USA 80526
970-493-1901 Fax: 970-493-1903
Email: sales@ixyscolorado.com
Web: http://www.ixyscolorado.com

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